





Light- and Elevated Temperature-Induced Degradation (LeTID): the Past, the Present and What Lies Ahead

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Daniel Chen

Faculty of Engineering

Moonyong Kim, Utkarshaa Varshney, Chandany Sen, Shaoyang Liu, Yuchao Zhang, Phillip Hamer, CheeMun Chong, Alison Ciesla, Catherine Chan, Ran Chen, Malcolm Abbott, Brett Hallam



Light- and Elevated Temperature Induced Degradation (LeTID)

• LeTID is now a very well known in both academia and industry



• There have been over 200 conference and journal publications worldwide



LeTID































Presentation Outline

- 1. A brief history of LeTID
- 2. Evaluating the Root Cause of LeTID
- 3. Our proposed LeTID model
- 4. Mitigation Strategies for LeTID
 Is LeTID going to be a problem for the industry?
 What happens after LeTID?



The Past – Beginnings of LeTID



Reference	Туре	Rel. Deg	Condition
Sio <i>et al.</i>	Cell	4.3%	65 °C, 1sun
Chan <i>et al.</i>	Cell	12.7%	70 °C, 0.46 kW/m²
Luka <i>et al.</i>	Cell	10%	75 °C, 1sun
Ramspeck et al.	Cell	6%	75 °C, 0.4 kW/m²
Petter <i>et al.</i>	Cell	16%	75 °C, 1sun
Deniz <i>et al.</i>	Cell	4.4%	75 °C, J _{SC}
Krauss <i>et al.</i>	Cell	11.2%	80 °C, 0.8 kW/m ²
Fertig <i>et al.</i>	Module	11%	85 °C, MPP, 1 kW/m²
Kersten <i>et al.</i>	Module	11%	85 °C, MPP
Nakayashiki <i>et al.</i>	Module	7.5%	Outdoor
Kersten <i>et al.</i>	Module	10%	Outdoor

- First identified in 2012 on mc-PERC solar cells by Ramspeck et al.
- Average degradation in efficiency of up to 10%_{rel} on **untreated cells** and as much as 16%_{rel} in some studies



The Past – Early Observations

• In 2015, Kersten et al. showed that the degradation was accelerated at higher T, thus calling it LeTID



- Later in 2017, Kwapil *et al.* demonstrated a dependence of the degradation reaction on Δn. Adding illumination increases the reaction rate.
- In 2017, Chan et al. observed that degradation also occurs during dark annealing



The Past – A Discovery of LeTID in Czochralski

• This provided a method of testing p-type Cz wafers without activating B-O defects



• As part of my PhD, we showed that LeTID also manifests itself in Cz materials



The Past – A Universal Defect in Silicon



[1] Sperber *et al.*, AIP Conf. Proc., 2019: p. 140011.
[2] Ramspeck et al., 27th EUPVSEC, (2012), 861-865.

[3] Duong *et al.*, Sol. Energy Mater. Sol. Cells. 188 (2018) 27–36.

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The Past – Evaluating the Root Cause – Metal Impurities

• In 2016, Bredemeier et al. proposed that metallic impurities (M) are the root cause of LeTID.



- **1.** Before firing: metallic impurities reside in a recombination inactive precipitated state (M_P) .
- **2.** Firing (T > 600 °C): precipitates dissolve into interstitials (M_i) .
- **3.** Cooldown: M_i bond with a homogeneously distributed impurity to form a $M_i X$ complex.
- **4.** Illuminated annealing: The complex reconfigures itself into a $M_i X^*$ complex then dissociates into M_i



The Past – Evaluating the Root Cause – Metal Impurities

- In 2017, Bredemeier et al. suggested Co and Ni as a possible metal impurity
- It was suggested that diffusion of the metals towards the surface could explain regeneration.



- Deniz et al. (2018), found Ni precipitation using TEM and energy dispersive x-ray (EDX) measurements.
- TIDLS by UNSW, MIT defect recombination properties (k-value) close to $Ti_i^{++/+}$, $Mo_i^{o/+}$ or $W_s^{o/+}$.

[1] Bredemeier *et al.*, Sol. RRL. 2 (2018) 1700159.
[2] Deniz *et al.*, Sol. RRL. 2 (2018) 1800170.

[3] Jensen *et al.*, 44th IEEE PVSC, 2017: pp. 3300–3303.



The Present – Hydrogen-Induced Degradation

• There are now many studies suggesting that hydrogen is responsible for LeTID.



- Recently, Schmidt et al. demonstrated for the first time, a direct correlation between [H] and LeTID
- In experiments, we observe different amounts of LeTID in different materials.
 - Is something inherent to the wafer also involved Could it be a H-X complex?



The Present – H-X Complexes and Deep Level Transient Spectroscopy

Temperature (K)

- Hydrogen can form complexes with almost everything
- Ag-H_X (Graff 2000...)
- Au-H (Deixier 1998...)
- **B-H** (Sah 1983...)
- **C-H** (Anderson 2002...)
- C-O-H (Vaqueiro-Contreras 2017)
- **Co-H**_X (Scheffler 2013...)
- **Cr-H** (Sadoh 1994...)
- Cu-H (Yarykin 2013...)
- Fe-H (Szwacki 2007...)
- Ni-H_x (Shiraishi 1999...)
- **P-H** (Seager 1990...)
- **Pd-H** (Jones 1999...)
- **Pt-H**_X (Hohne 1994...)
- Si-V-H_X & Si-V-O-H_X (Bonde 1999)
- **Ti-H_X** (Scheffler 2015...)
- V_X-H_Y (Graff 2000...)
- **Va-H**_X (Sadoh 1992...)
- And many more.....



DLTS is a good method for identifying recombination active traps

• Recent DLTS studies have hypothesised that **Fe-H** or **C-H** complexes may be defect behind LeTID. Further measurements are needed to confirm this.

100



300

200

T (K)

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The Present – A Hydrogen-X Defect Model



• **During firing (peak)** – H diffuses into Si as interstitials





The Present – A Hydrogen-X Defect Model



- During firing (peak) H diffuses into Si as interstitials
- At high temperatures, the Si conductivity is intrinsic \rightarrow H is largely in the H⁺ state







• **During cooling (quenching)** – H forms B-H pairs in the bulk and passivates defects.





- At high temperatures, the Si conductivity is intrinsic \rightarrow H is largely in the H⁺ state
- During cooling (quenching) H forms B-H pairs in the bulk and passivates defects.
- It also pre-forms LeTID, however, a majority of H is frozen in metastable dimer states ($H_{2A/B}$)





- During annealing or light soaking H_{2A} dimers dissociate and contribute to B-H and LeTID
- All of these bonds are metastable and constantly breaking and forming e.g. H⁺ + B-H → H_{2B/C} + B⁻ + 2h⁺





The Present – A Hydrogen-X Defect Model

Si H

H0

N



- Net motion of H is towards the surface and out of silicon.
- With long-duration annealing, H effuses out of wafer or transforms into a stable H_{2C} dimer state.
- LeTID recovers when the bulk is depleted of metastable dimers, bound states and H interstitials



[1] Fung *et al.*, AIP Conf. Proc., 2018: p. 130004.

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The Present – Mitigation of LeTID – Process Modification

• There are many ways of reducing the hydrogen content within the silicon wafers to reduce LeTID



- Reducing peak firing \rightarrow Less H in-diffusion or Slower-cooling \rightarrow More H effusion
- Thinner wafers have demonstrated lower LeTID ightarrow Faster defect effusion



The Present – Mitigation of LeTID – Process Modification

- We can also reduce the hydrogen content within the SiN_x:H films.
- Reducing the thickness of SiN_X:H \rightarrow lower Si-H and N-H bond density \rightarrow lower [H] released during firing
- Deposition of <u>ALD</u> AlO_X under the SiN_X:H as barrier for hydrogen in-diffusion



[1] Varshney *et al.*, IEEE J. Photovoltaics. 9 (2019) 601–607.
[2] Varshney *et al.*, *IEEE J. Photovoltaics*, 2019 (in press)



The Present – Mitigation of LeTID – Process Modification

- Tuning the SiN_x:H refractive index to release less hydrogen during firing
- At low RI < 1.9, SiN_X:H films have high atomic density \rightarrow reduces H diffusivity
- Hydrogen is important as it allows for the passivation of bulk defects (e.g. B-O in p-type)
- Lower [H] causes B-O regeneration to become slower → LID mitigation techniques become less effective.



- Commercial LeTID
 mitigation usually involves
 post-cell treatments
- 1. Light based treatments
- 2. Current Injection
- 3. Biased annealing

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[1] Bredemeier *et al.*, Phys. Status Solidi – Rapid Res. Lett. 13 (2019) 1900201.
[2] Wilking et al., J. Appl. Phys. 114 (2013) 194512



The Present – An Example of Commercial ANTI-LeTID Solar Cells and Modules



- Risen solar (Jäger Series) combine many techniques
- 1. Low temperature firing reduces hydrogen in-diffusion
- 2. Current-injection post-cell processing
- 3. ALD AIO_x : H passivation on both sides hydrogen lean blocking layer
- 4. SiO₂ layer on both sides hydrogen blocking layer







What Lies Ahead – Will LeTID Remain a Problem for Commercial PV?



LeTID is both a material-inherent and process-induced defect

- Wafer quality is constantly improving with some wafers that are already LeTID free.
- Choosing better wafer sources + applying mitigation treatments will solve LeTID in both mc-Si and Cz-Si



What Lies Ahead – Hydrogen-Induced Surface Degradation

- As LeTID recovers, hydrogen diffuses out towards the surfaces.
- Too much H at the interface can lead to the formation of hydrogen-induced defects → surface degradation (increased J_{0s}).
- On PERC cells, this long-term degradation can cause up to a 10% absolute drop in efficiency due to an decrease in FF [1].









Summary

- LeTID is a complicated but well understood problem.
- There are many mitigation techniques for commercial PERC solar cell
- Beyond LeTID, we need to start assessing the impact of hydrogen-induced surface degradation and finding solutions.
- I hope that you have learnt something from my talk!





Thank you for your attention. <u>Daniel.chen@unsw.edu.au</u>



